AN APPARATUS TO QUANTIFY THE ADHESION OF FILM

ABSTRACT

A new apparatus is provided for the quantification of the adhesion of a film over a substrate. In particular, the peeling force and the rate of peeling are quantified by providing a first means for measuring the peeling force, a second means for measuring the rate of peeling, a third means for securing a piece of wafer, an adhesive tape, a tape holder and a resilient, flexible component.

Fig. 3